

OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS GATES

Check for Samples: [SN54AHC541](#), [SN74AHC541](#)

FEATURES

- Operating Range 2-V to 5.5-V V_{CC}
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

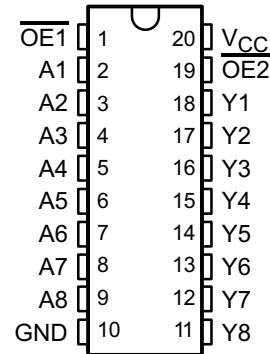
DESCRIPTION

The 'AHC541 octal buffers/drivers are ideal for driving bus lines or buffer memory address registers. These devices feature inputs and outputs on opposite sides of the package to facilitate printed circuit board layout.

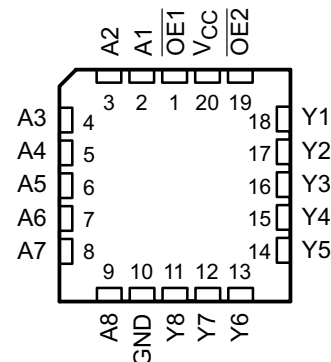
The 3-state control gate is a two-input AND gate with active-low inputs so that if either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all corresponding outputs are in the high-impedance state. The outputs provide noninverted data when they are not in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54AHC541 . . . J OR W PACKAGE
SN74AHC541 . . . DB, DGV, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHC541 . . . FK PACKAGE
(TOP VIEW)



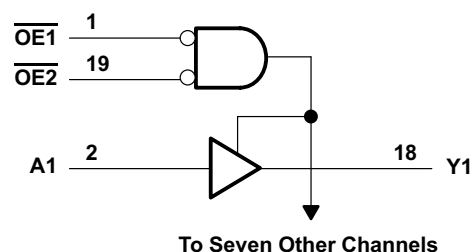
**FUNCTION TABLE
(EACH BUFFER/DRIVER)**

INPUTS			OUTPUT Y
$\overline{OE1}$	$\overline{OE2}$	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		VALUE	UNIT
Supply voltage range, V_{CC}		–0.5 to 7	V
Input voltage range, V_I ⁽²⁾		–0.5 to 7	V
Output voltage range, V_O ⁽²⁾		–0.5 to $V_{CC} + 0.5$	V
Input clamp current, I_{IK} ($V_I < 0$)		–20	mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)		±20	mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25	mA
Continuous current through V_{CC} or GND		±75	mA
Package thermal impedance, θ_{JA} ⁽³⁾	DB package	70	°C/W
	DGV package	92	
	DW package	58	
	N package	69	
	NS package	60	
	PW package	83	
Storage temperature range, T_{stg}		–65 to 150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			SN54AHC541		SN74AHC541		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	5.5	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5		V
		V _{CC} = 3 V	2.1		2.1		
		V _{CC} = 5.5 V	3.85		3.85		
V _{IL}	Low-level Input voltage	V _{CC} = 2 V		0.5		0.5	V
		V _{CC} = 3 V		0.9		0.9	
		V _{CC} = 5.5 V		1.65		1.65	
V _I	Input voltage		0	5.5	0	5.5	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V		–50		–50	mA
		V _{CC} = 3.3 V ± 0.3 V		–4		–4	
		V _{CC} = 5 V ± 0.5 V		–8		–8	
I _{OL}	Low-level output current	V _{CC} = 2 V		50		50	mA
		V _{CC} = 3.3 V ± 0.3 V		4		4	
		V _{CC} = 5 V ± 0.5 V		8		8	
Δt/Δv	Input Transition rise or fall rate	V _{CC} = 3.3 V ± 0.3 V		100		100	ns/V
		V _{CC} = 5 V ± 0.5 V		20		20	
T _A	Operating free-air temperature		–55	125	–40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = –55°C TO 125°C		T _A = –40°C TO 85°C		T _A = –40°C TO 125°C		UNIT
										Recommended		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –50 μA	2 V	1.9	2		1.9		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		4.4		
	I _{OH} = –4 mA	3 V	2.58		2.48		2.48		2.48			
	I _{OH} = –8 mA	4.5 V	3.94		3.8		3.8		3.8			
V _{OL}	I _{OL} = 50 μA	2 V			0.1		0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1		0.1	
	I _{OH} = 4 mA	3 V		0.36		0.5		0.44		0.5		
	I _{OH} = 8 mA	4.5 V		0.36		0.5		0.44		0.5		
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1 ⁽¹⁾		±1		±1	μA
I _{OZ} ⁽²⁾	V _O = V _{CC} or GND V _I (OE) = V _{IL} or V _{IH}	5.5 V			±0.25		±2.5		±2.5		±2.5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		40		40		20	μA
C _i	V _I = V _{CC} or GND	5 V		2	10				10			pF
C _O	V _O = V _{CC} or GND	5V		4								pF

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

(2) For input and output, I_{OZ} includes the input leakage current.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C		T _A = −55°C TO 125°C		T _A = −40°C TO 85°C		T _A = −40°C TO 125°C		UNIT
						Recommended						
				SN54AHC541	SN74AHC541	SN74AHC541						
				TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF	5 ⁽¹⁾	7 ⁽¹⁾	1 ⁽¹⁾	8.5 ⁽¹⁾	1	8.5	1	8.5	ns
t _{PHL}				5 ⁽¹⁾	7 ⁽¹⁾	1 ⁽¹⁾	8.5 ⁽¹⁾	1	8.5	1	8.5	
t _{PZH}	OE	Y	C _L = 15 pF	6 ⁽¹⁾	10.5 ⁽¹⁾	1 ⁽¹⁾	11 ⁽¹⁾	1	11	1	11	ns
t _{PZL}				6 ⁽¹⁾	10.5 ⁽¹⁾	1 ⁽¹⁾	11 ⁽¹⁾	1	11	1	11	
t _{PHZ}	OE	Y	C _L = 15 pF	7 ⁽¹⁾	11 ⁽¹⁾	1 ⁽¹⁾	12 ⁽¹⁾	1	12	1	12	ns
t _{PLZ}				7 ⁽¹⁾	11 ⁽¹⁾	1 ⁽¹⁾	12 ⁽¹⁾	1	12	1	12	
t _{PLH}	A	Y	C _L = 50 pF	7.5	10.5	1	12	1	12	1	12	ns
t _{PHL}				7.5	10.5	1	12	1	12	1	12	
t _{PZH}	OE	Y	C _L = 50 pF	8	14	1	16	1	16	1	16	ns
t _{PZL}				8	14	1	16	1	16	1	16	
t _{PHZ}	OE	Y	C _L = 50 pF	9	15.4	1	17.5	1	17.5	1	17.5	ns
t _{PLZ}				9	15.4	1	17.5	1	17.5	1	17.5	
tsk(o)			C _L = 50 pF	1.5 ⁽²⁾		1		1.5				ns
t _{PLH}	A or B	Y	C _L = 50 pF	6.3	8.8	1	10	1	10	1	10	ns
t _{PHL}				6.3	8.8	1	10	1	10	1	10	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

(2) On products compliant to MIL-PRF-38535, this parameter does not apply

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		T _A = -40°C TO 125°C		UNIT
						Recommended						
				SN54AHC541		SN74AHC541		SN74AHC541				
				TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF	3.5 ⁽¹⁾	5.0 ⁽¹⁾	1 ⁽¹⁾	6 ⁽¹⁾	1	6	1	6	ns
t _{PHL}				3.5 ⁽¹⁾	5.0 ⁽¹⁾	1 ⁽¹⁾	6 ⁽¹⁾	1	6	1	6	
t _{PZH}	$\overline{OE}$	Y	C _L = 15 pF	4.7 ⁽¹⁾	7.2 ⁽¹⁾	1 ⁽¹⁾	8.5 ⁽¹⁾	1	8.5	1	8.5	ns
t _{PZL}				4.7 ⁽¹⁾	7.2 ⁽¹⁾	1 ⁽¹⁾	8.5 ⁽¹⁾	1	8.5	1	8.5	
t _{PHZ}	$\overline{OE}$	Y	C _L = 15 pF	5.0 ⁽¹⁾	7.5 ⁽¹⁾	1 ⁽¹⁾	8 ⁽¹⁾	1	8	1	8	ns
t _{PLZ}				5.0 ⁽¹⁾	7.5 ⁽¹⁾	1 ⁽¹⁾	8 ⁽¹⁾	1	8	1	8	
t _{PLH}	A	Y	C _L = 50 pF	5.0	7.0	1	8	1	8	1	8	ns
t _{PHL}				5.0	7.0	1	8	1	8	1	8	
t _{PZH}	$\overline{OE}$	Y	C _L = 50 pF	6.2	9.2	1	10.5	1	10.5	1	10.5	ns
t _{PZL}				6.2	9.2	1	10.5	1	10.5	1	10.5	
t _{PHZ}	$\overline{OE}$	Y	C _L = 50 pF	6.0	8.8	1	10	1	10	1	10	ns
t _{PLZ}				6.0	8.8	1	10	1	10	1	10	
tsk(o)			C _L = 50 pF	1 ⁽²⁾		1		1				ns

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

(2) On products compliant to MIL-PRF-38535, this parameter does not apply

NOISE CHARACTERISTICS

 $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}^{(1)}$

PARAMETER		SN74AHC541		UNIT
		MIN	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		–0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}	4.7		V
$V_{IH(D)}$	High-level dynamic input voltage	3.5		V
$V_{IL(D)}$	Low-level dynamic input voltage		1.5	V

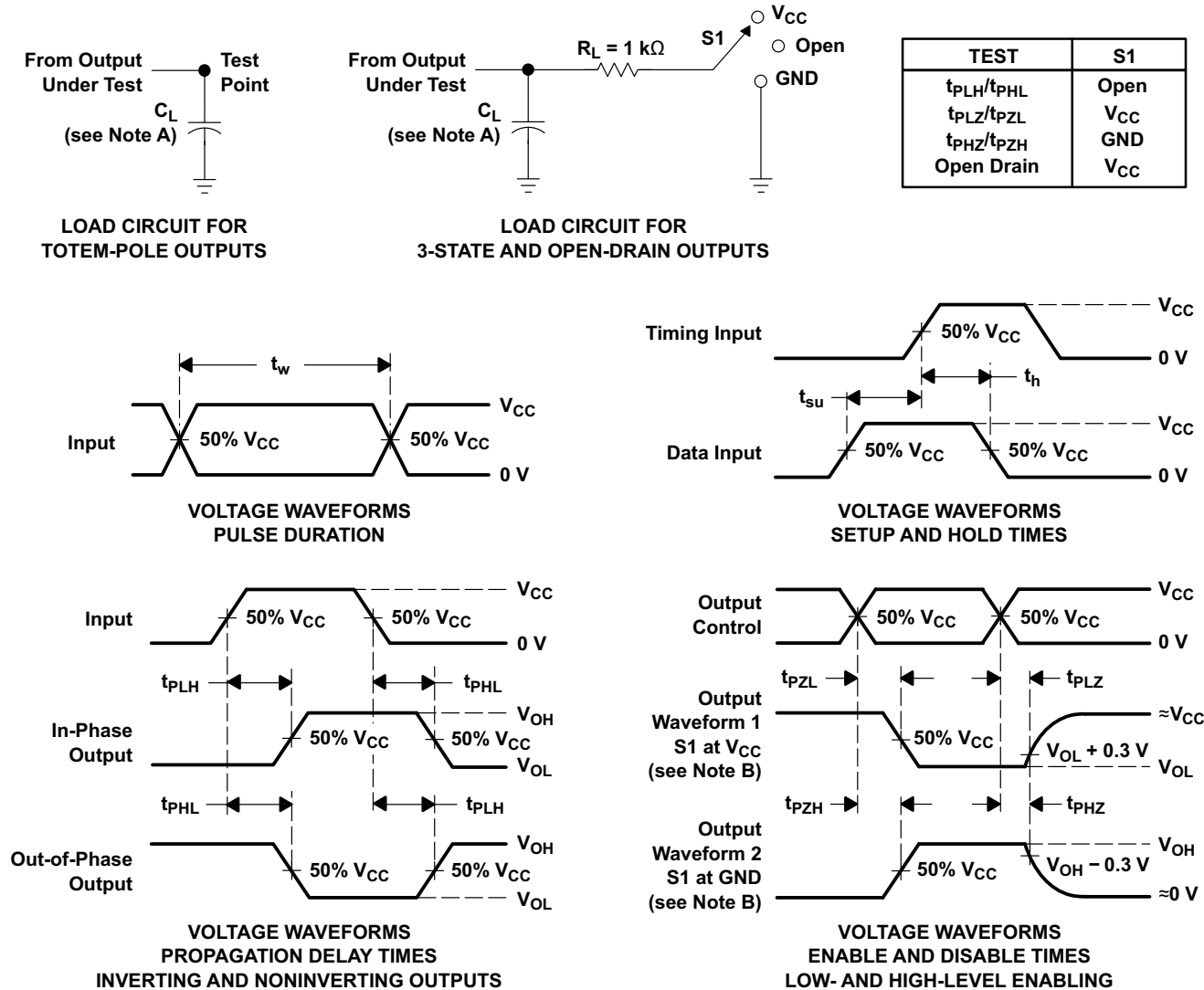
(1) Characteristics are for surface-mount packages only.

OPERATING CHARACTERISTICS

 $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	$f = 1\text{ MHz}$	12	pF

PARAMETER MEASUREMENT INFORMATION



- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

REVISION HISTORY

Changes from Revision M (July 2003) to Revision N	Page
• Changed document format from Quicksilver to DocZone.	1
• Extended operating temperature range to 125°C	3

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9685701Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9685701Q2A SNJ54AHC 541FK	Samples
5962-9685701QRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9685701QR A SNJ54AHC541J	Samples
5962-9685701QSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9685701QS A SNJ54AHC541W	Samples
SN74AHC541DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	-40 to 125		
SN74AHC541DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SN74AHC541DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SN74AHC541DGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SN74AHC541DGVRG4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SN74AHC541DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC541	Samples
SN74AHC541DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC541	Samples
SN74AHC541DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC541	Samples
SN74AHC541N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	SN74AHC541N	Samples
SN74AHC541NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC541	Samples
SN74AHC541PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SN74AHC541PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SN74AHC541PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 125		

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHC541PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SN74AHC541PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SN74AHC541PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HA541	Samples
SNJ54AHC541FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9685701Q2A SNJ54AHC 541FK	Samples
SNJ54AHC541J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9685701QR A SNJ54AHC541J	Samples
SNJ54AHC541W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9685701QS A SNJ54AHC541W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54AHC541, SN74AHC541 :

- Catalog: [SN74AHC541](#)
- Automotive: [SN74AHC541-Q1](#), [SN74AHC541-Q1](#)
- Military: [SN54AHC541](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC541DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHC541DGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHC541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AHC541NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AHC541PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74AHC541PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC541DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74AHC541DGVR	TVSOP	DGV	20	2000	367.0	367.0	35.0
SN74AHC541DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AHC541NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AHC541PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74AHC541PWR	TSSOP	PW	20	2000	364.0	364.0	27.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

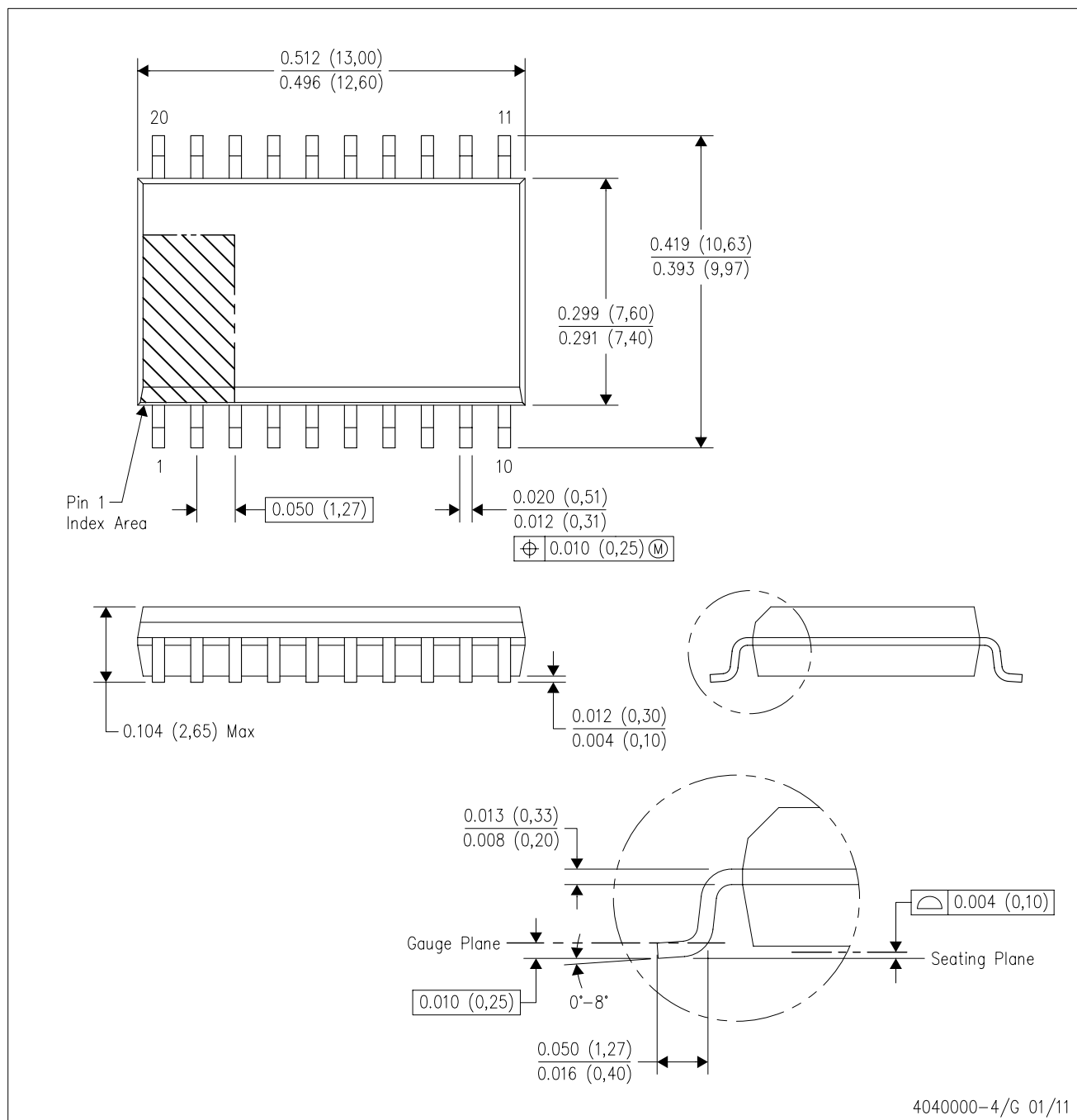
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G20)

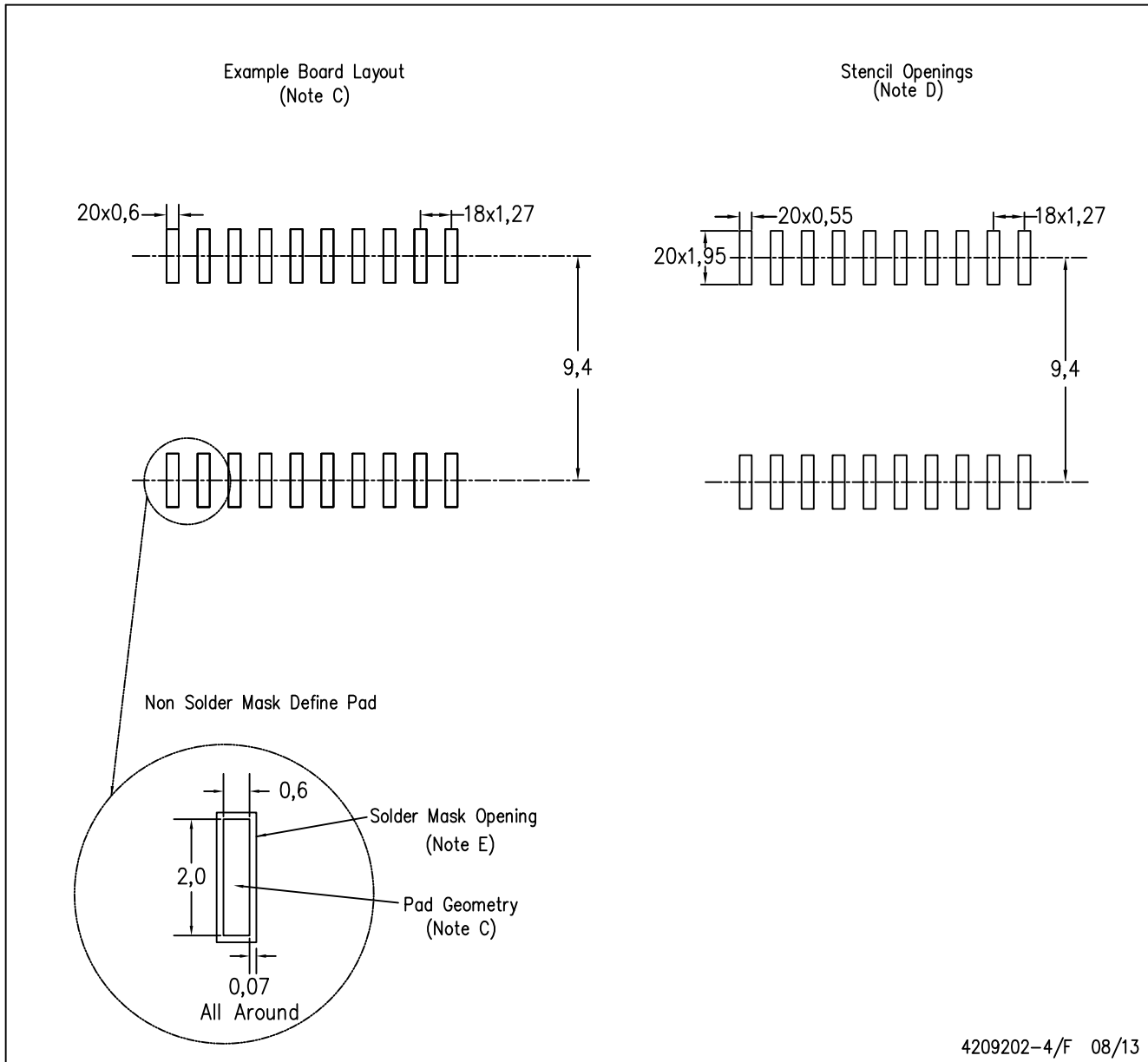
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

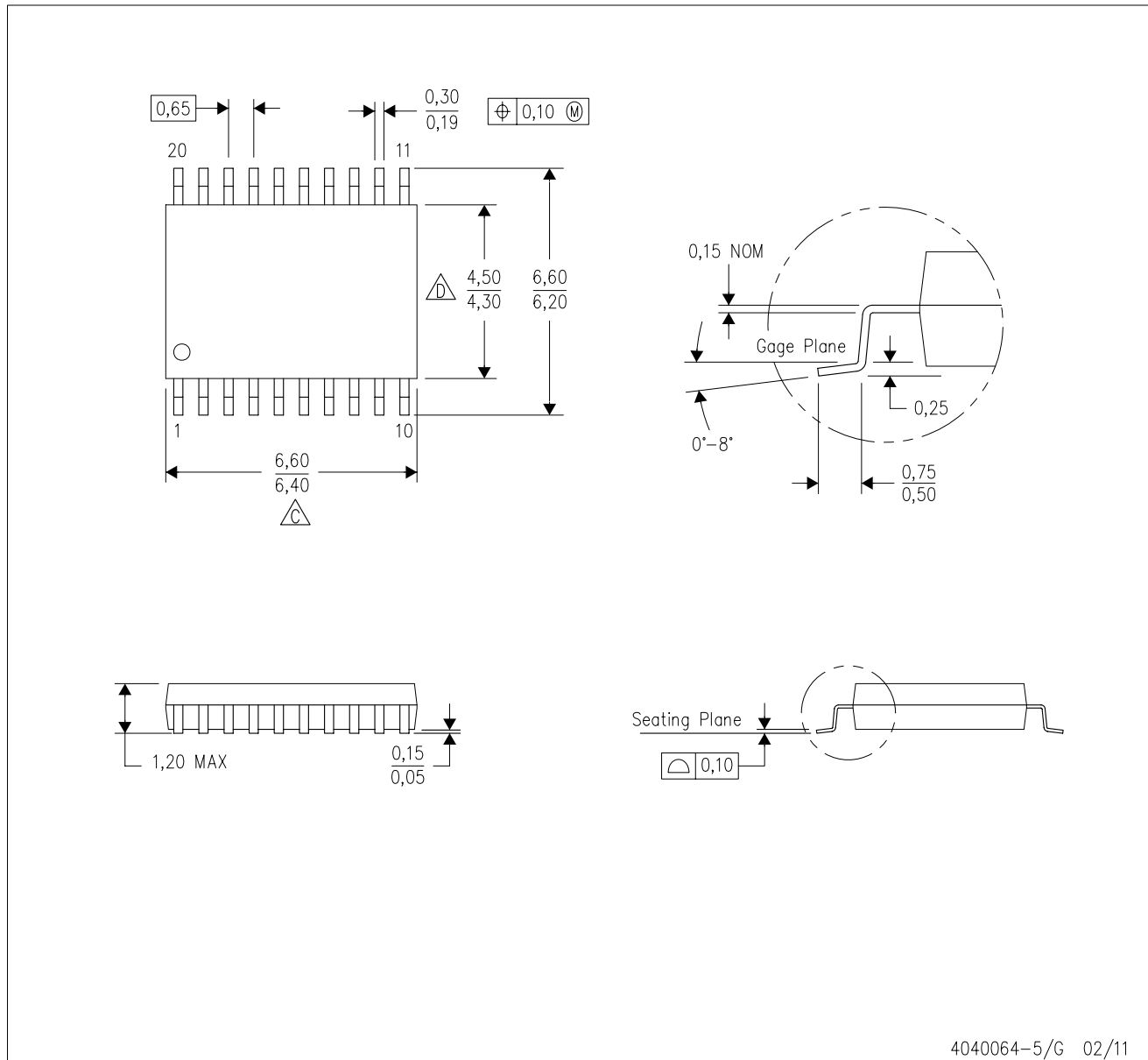
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4040064-5/G 02/11

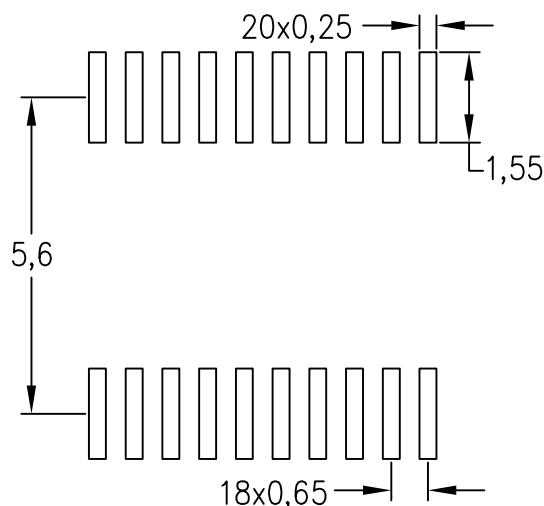
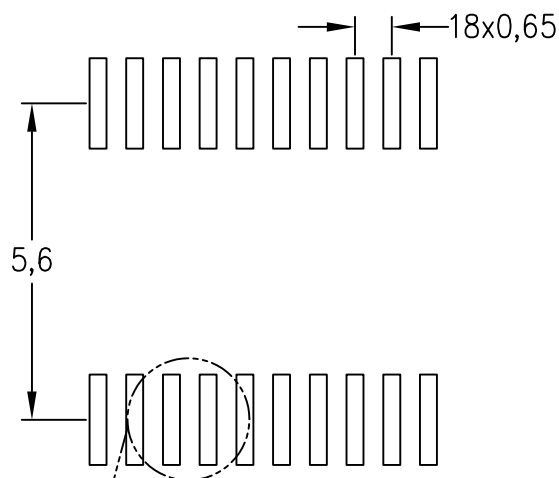
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

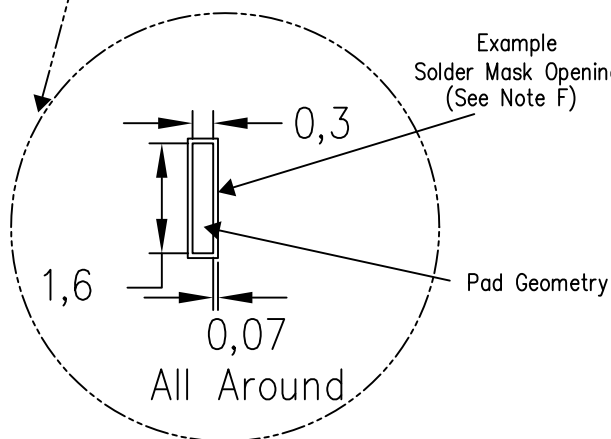
Example Board Layout

Based on a stencil thickness
of .127mm (.005inch).



Example
Non Soldermask Defined Pad

Example
Solder Mask Opening
(See Note F)



4211284-5/F 12/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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